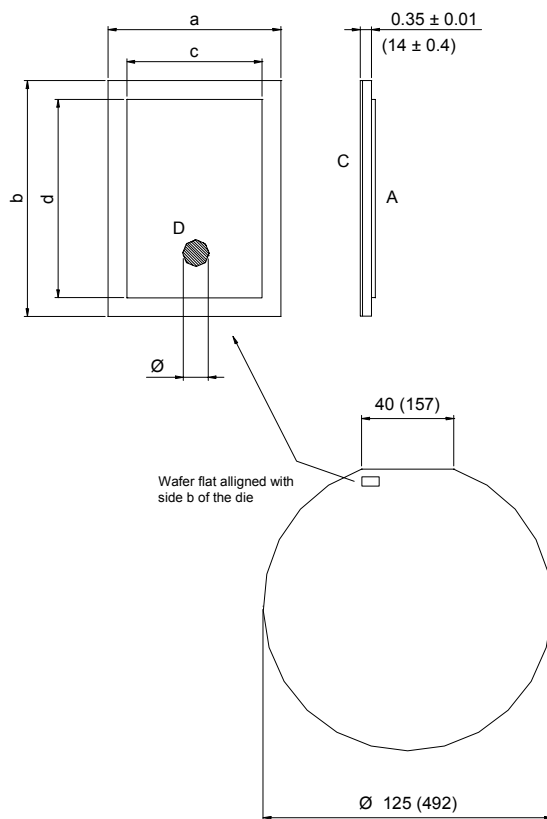


SCHOTTKY DIE 105 x 125 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (MILS).
2. CONTROLLING DIMENSION: (MILS).
3. DIMENSIONS AND TOLERANCES:
 $a = 3.18 + 0, - 0.01$
 $(125 + 0, - 0.4)$
 $b = 2.67 + 0, - 0.01$
 $(105 + 0, - 0.4)$
 $c = 3.02 + 0, - 0.01$
 $(119 + 0, - 0.4)$
 $d = 2.51 + 0, - 0.01$
 $(99 + 0, - 0.4)$
 $\varnothing = 1 \pm 0.15$
 (40 ± 6)
4. LETTER DESIGNATION:
 A = Anode (Top Metal)
 C = Cathode (Back Metal)
 D = Reject Ink Dot (only on non-conforming dies)
5. SAWING:
 Recommended Blade
 SEMITEC S1025 QS00 Blade
 Sawing Street
 $0.05 + 0, - 0.005$
 $(2 + 0, - 0.2)$

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
Contact factory for information.

SC105.....5. Series

Bulletin I0503J rev. C 05/01

International
IOR Rectifier

Electrical Characteristics

Device #	T _J Max. (°C)	V _R (V)	Typ. I _R @ 25°C (μA)	Typ. I _R @ 125°C (mA)	Max. V _F @ I _F (V)	Package Style
SC105 R 015x5x	125	15	n.a. contact factory			
SC105 S 020x5x	150	20	700	180	0.51 @ 40A	TO-220
SC105 S 030x5x	150	30	220	100	0.49 @ 15A	TO-220
SC105 S 045x5x	150	45	150	75	0.54 @ 15A	TO-247
SC105 S 060x5x	150	60	110	60	0.60 @ 15A	TO-247
SC105 H 045x5x	175	45	35	10	0.62 @ 15A	TO-220
SC105 H 100x5x	175	100	12	7	0.86 @ 15A	TO-247
SC105 H 150x5x	175	150	15	10	1.0 @ 15A	TO-220

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC105xxxx A 5x	Bondable	–	Al/Si 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC105xxxx S 5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.

Shelf life for parts stored in above condition is 2 years.

If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

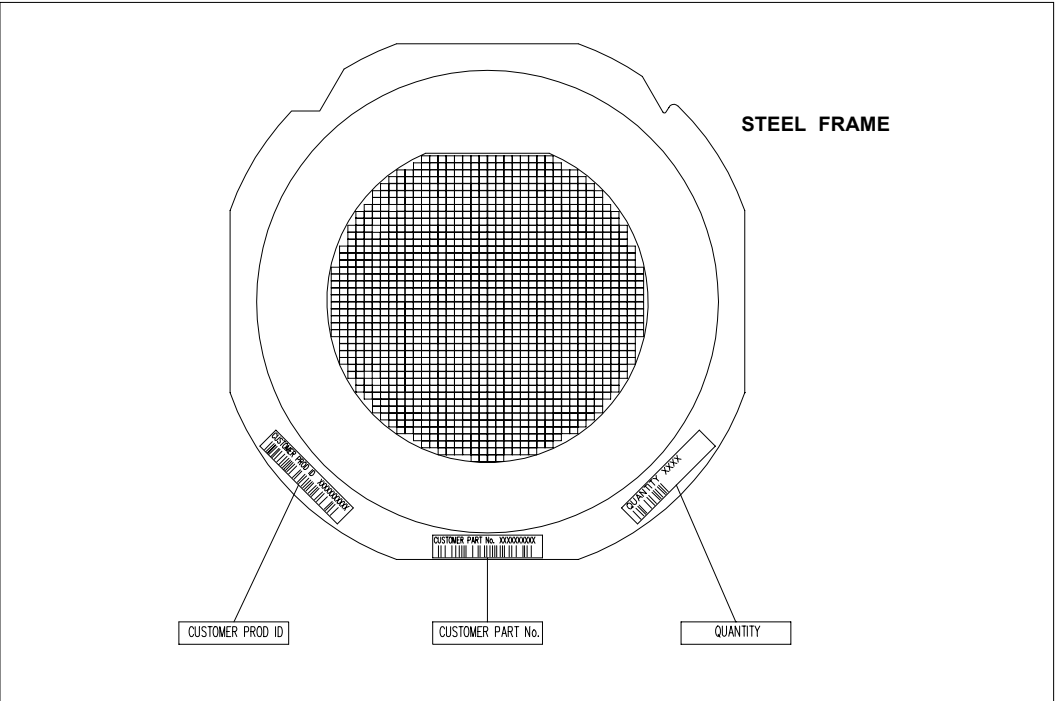
Device #	Description	Minimum Order Quantity Die in Sale Package
SC105xxxxx B	Inked Probed Unsawn Wafer (Wafer in Box)	1170
SC105xxxxx R	Probed Die in Tape & Reel	8,000
SC105xxxxx P	Probed Die in Waffle Pack	1170
SC105xxxxx F	Inked Probed Sawn Wafer on Film	1170

Ordering Information Table

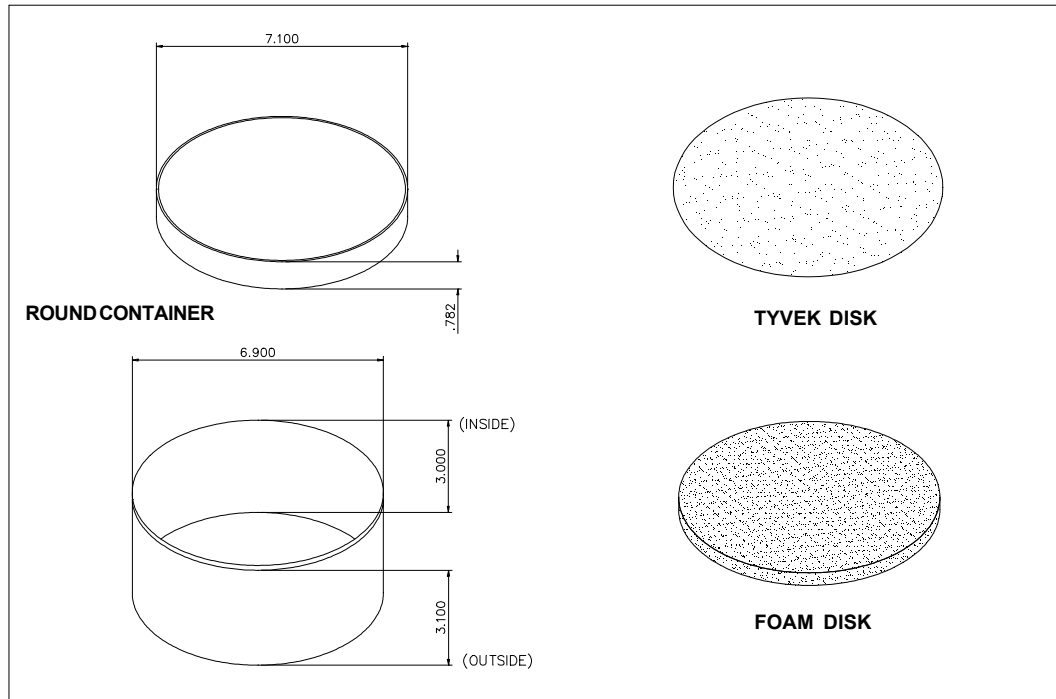
Device Code						
SC	105	H	100	S	5	B
1	2	3	4	5	6	7
1	- Schottky Die					
2	- Chip Dimension in Mils					
3	- Process (see Electrical Characteristics Table)					
4	- Voltage code: Code = V_{RRM}					
5	- Chip surface metallization (see Mechanical Data Table)					
6	- Wafer Diameter in inches					
7	- Packaging (see Packaging Table)					

H = 830 Process
R = OR'ing Process
S = Standard Process

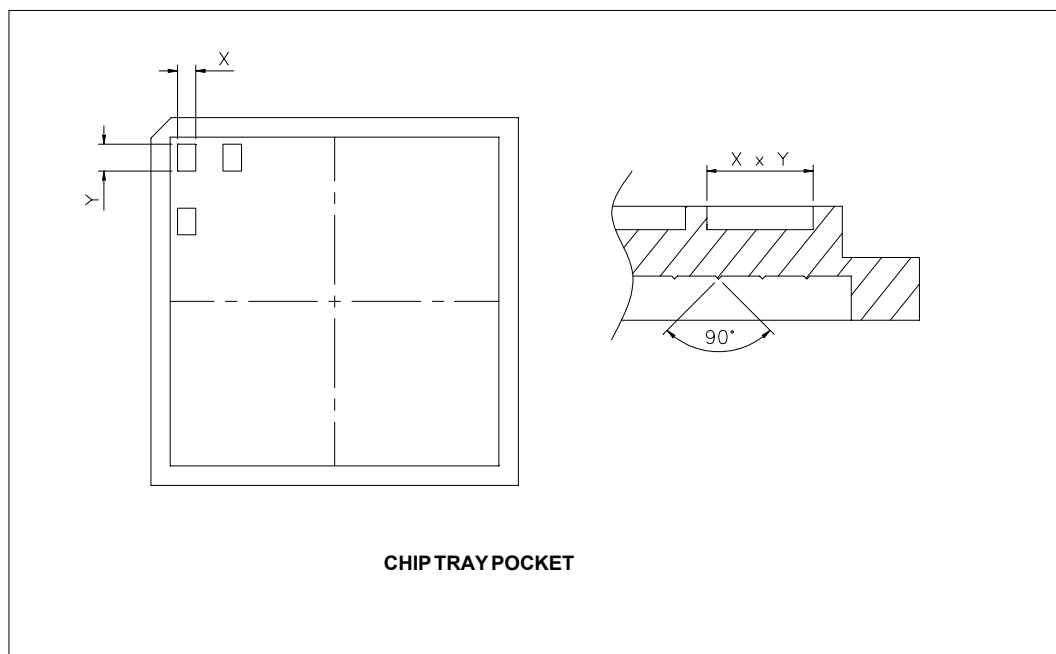
Wafer on Film



Wafer in Box



Die in Waffle Pack



Tape and Reel

